

## What is claimed is:

- [Claim 1] 1. A method of forming a light guide plate insert mold, comprising:
- providing a substrate;
  - performing a surface treating process upon the substrate;
  - forming a plurality of photo resist patterns on the substrate;
  - performing a flow process so as to form a microlens surface on each photo resist pattern; and
  - forming a metal layer on the photo resist patterns so as to form a plurality of patterns complementary to the photo resist patterns on a bottom surface of the metal layer.
- [Claim 2] 2. The method of claim 1, wherein before the surface treating process is performed the method further comprises:
- performing a rinsing process; and
  - performing a dehydrating process.
- [Claim 3] 3. The method of claim 1, wherein the surface treating process is a thin film deposition process for forming a metal thin film on the substrate.
- [Claim 4] 4. The method of claim 3, wherein the thin film deposition process is selected from technologies consisting of physical vapor deposition, chemical vapor deposition, electroplating, and electroless plating.
- [Claim 5] 5. The method of claim 1, wherein the surface treating process is a roughening process for altering the roughness of the substrate.
- [Claim 6] 6. The method of claim 5, wherein the roughening process is selected from technologies consisting of blasting treatment and etching treatment.

[Claim 7] 7. The method of claim 1, wherein the surface treating process is a surface activating process for altering the surface energy of the substrate.

[Claim 8] 8. The method of claim 7, wherein the surface activating process is selected from technologies consisting of plasma bombing and surfactant treatment.

[Claim 9] 9. The method of claim 1, wherein the surface treating process is a coating process for forming a photo resist film on the substrate.

[Claim 10] 10. The method of claim 1, wherein the step of forming the photo resist patterns further comprises:

coating a photo resist layer onto the substrate; and  
performing an exposing and developing process to remove a portion of the photo resist layer.

[Claim 11] 11. The method of claim 1, wherein the surface treating process acts upon the entire substrate.

[Claim 12] 12. The method of claim 1, wherein the surface treating process partially acts upon the substrate.

[Claim 13] 13. The method of claim 1, wherein the metal layer is formed by electroplating.

[Claim 14] 14. The method of claim 1, wherein after the metal layer is formed the method further comprises a step of departing the metal layer from

the substrate and the photo resist patterns so as to form the light guide plate insert mold.